

# **RAD Engineering BLM VME J2 Backplane**

## **Printed Circuit Board Trace Impedance Measurements**

**February 8, 2005**

# Test Equipment Used

- ⇒ RAD Engineering VME J2 Backplane
- ⇒ Scope: HP 54825A Infinium Oscilloscope 500MHz 2 Ga/s
- ⇒ Probes: HP 1160A Probes (500 MHz, 10 Meg Ohm, 9pf)
- ⇒ Pulse Generator: HP 8131A, 500 MHz
- ⇒ Assortment of Fixed Resistors / Variable

# Input Pulse Parameters

- ⇒ Input pulse has a 850ps rise time.
- ⇒ Pulse Period 500 $\mu$ s, Pulse High width 10 $\mu$ s.
- ⇒ Pulse Level High = 5.00V
- ⇒ Pulse Level Low = 0.20V
- ⇒ Pulse Generator output terminated with a 52.5 Ohm and a 1.00 K Ohm series resistor to make a current source.

# Initial Impedance Measurements

⇒ Impedance measurements were carried out on the following backplane traces.

⇒ Row A pins 17 (Signal) and 18 (Gnd).

⇒ Row B pins 11 (Signal) and 12 (Gnd).

⇒ Row C pins 29 (Signal) and 30 (Gnd)

⇒ **Notes:** The A and C-Rows are the BLM Control Bus. B-Row is the standard VME J2 pinout.

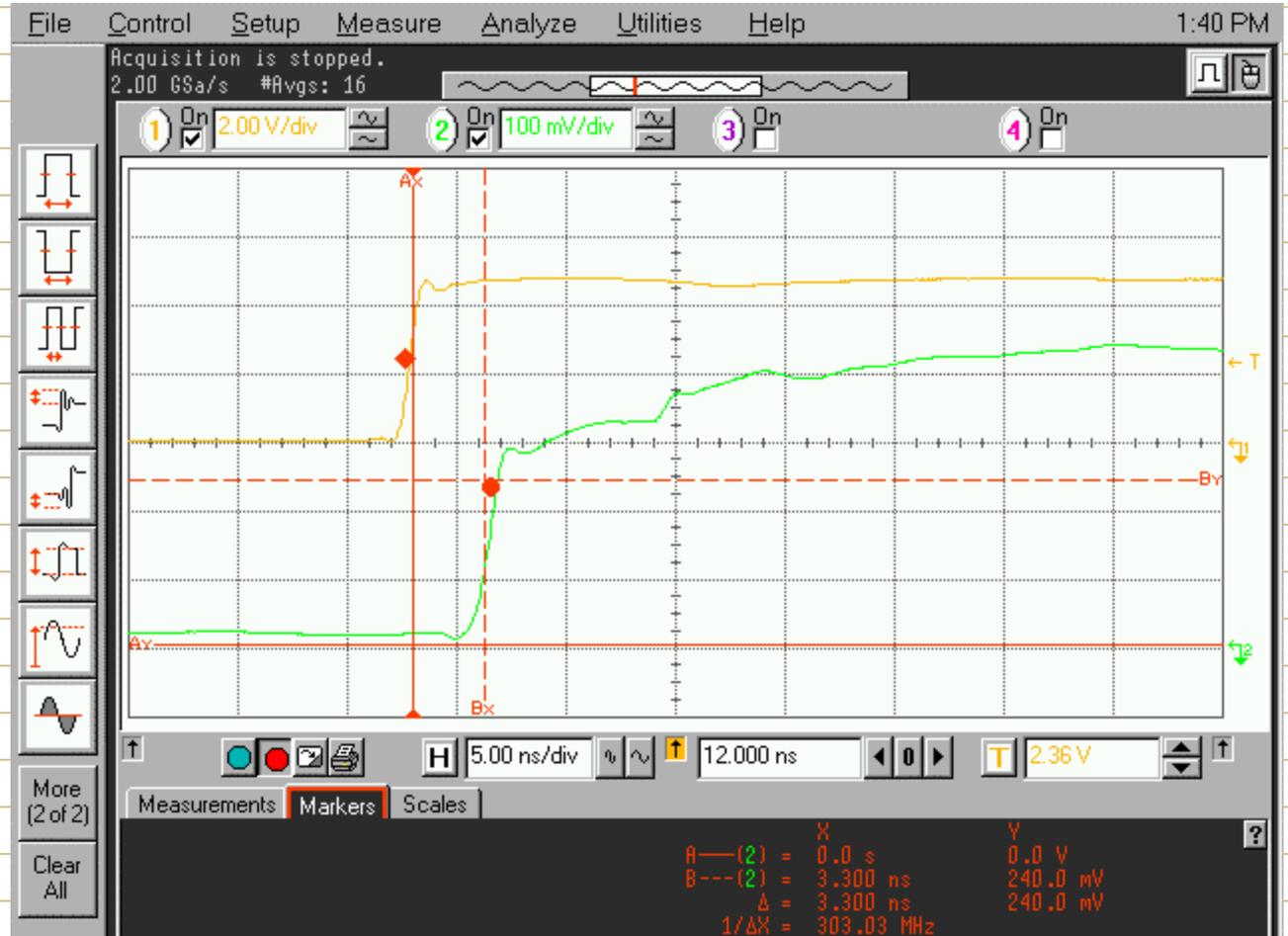
⇒ The A and C-Row traces are on outer signal layers. The B-Row traces are on an inner signal layer.

# Impedance Row A pins

File Name:

impA\_100.TIF

Trace terminated in 100 ohm resistor.



# Impedance Row A pins

File Name:

impA\_073.TIF

Trace  
terminated in  
72.7 ohm  
resistor.

(70 Ohms - Stephen  
Request)

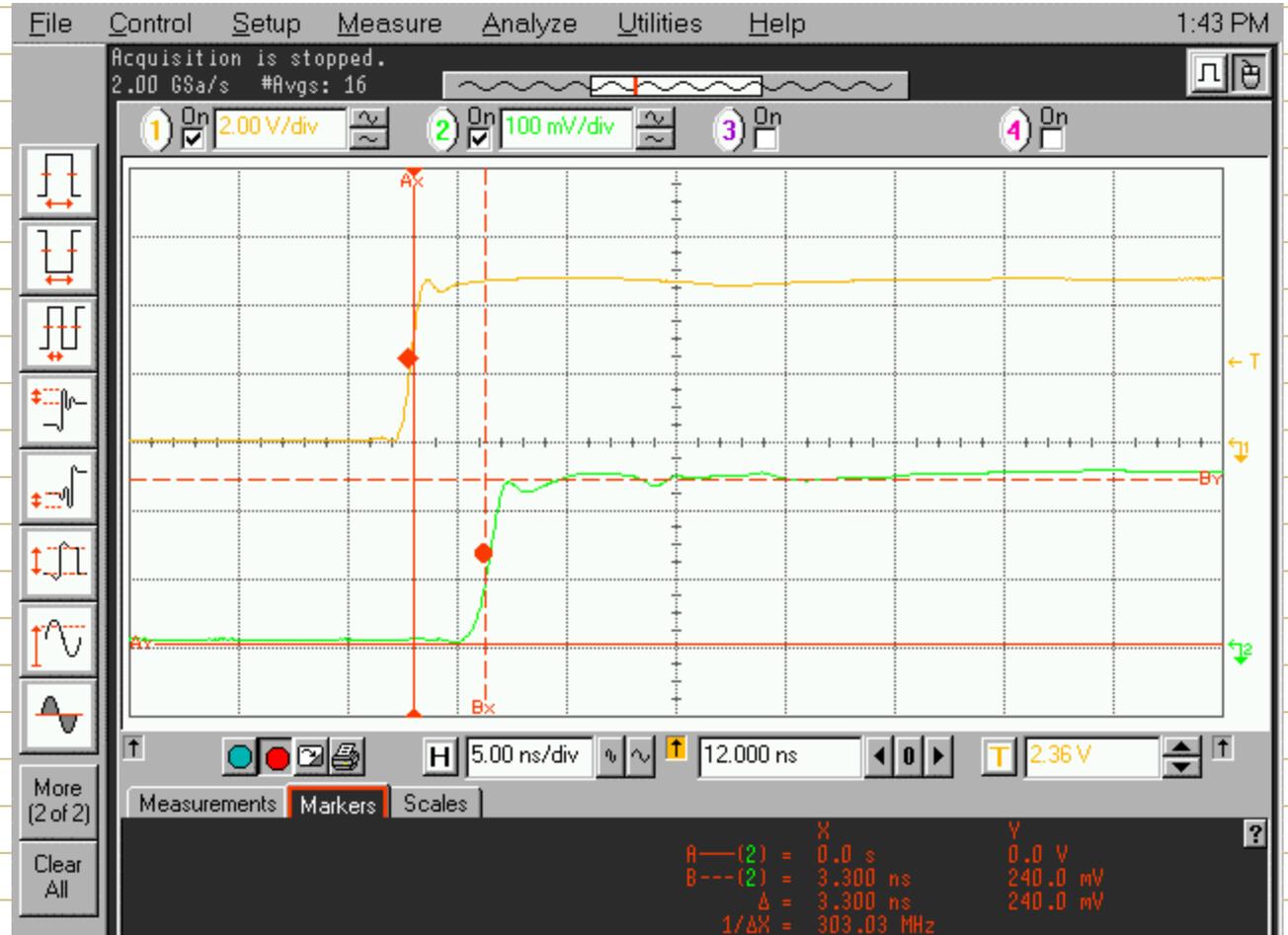


# Impedance Row A pins

File Name:

impA\_056.TIF

Trace terminated in 56.5 ohm resistor.



# Impedance Row A pins

File Name:

impA\_042.TIF

Trace terminated in 42 ohm resistor.

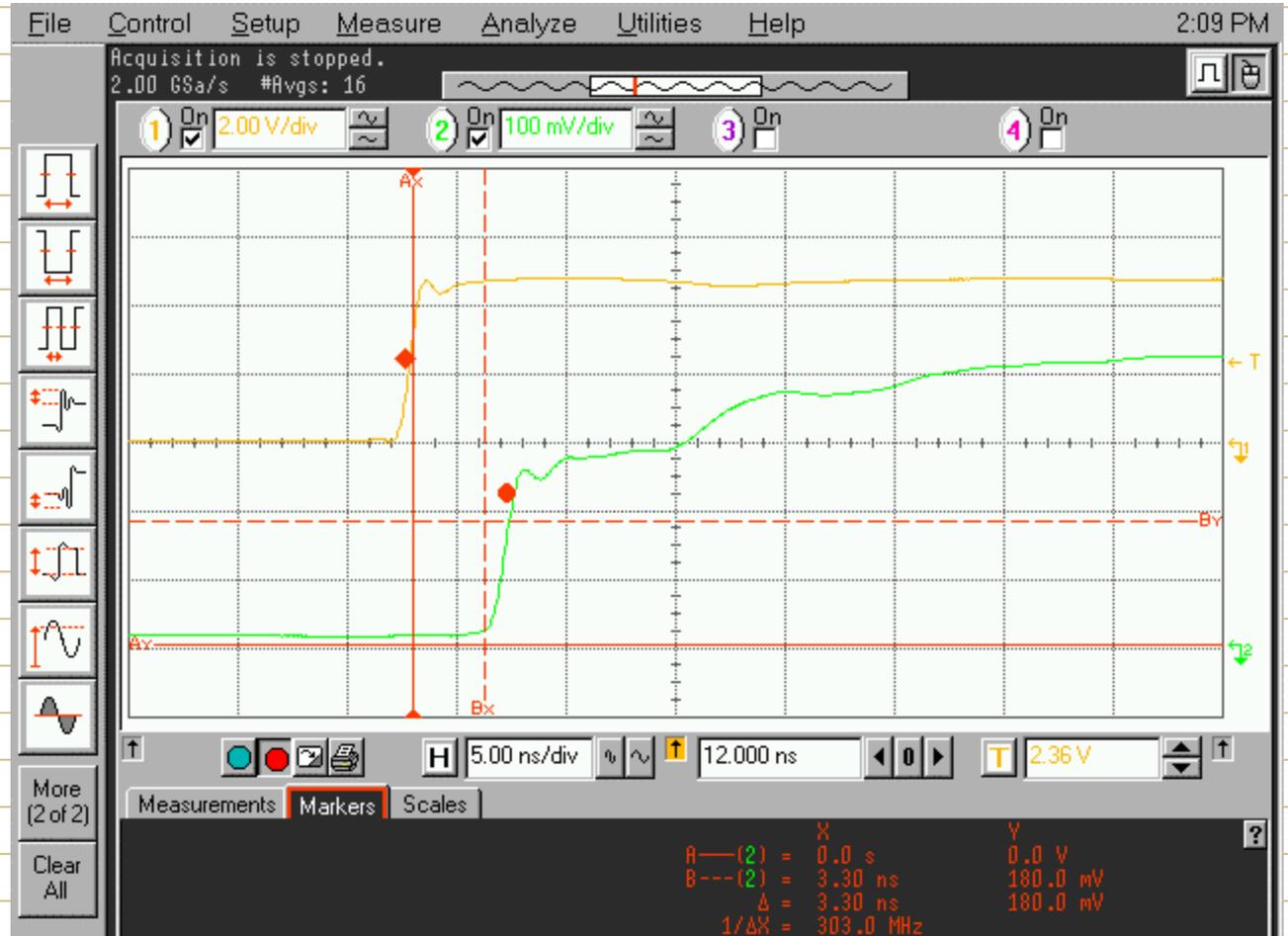


# Impedance Row B pins

File Name:

impB\_100.TIF

Trace terminated in 100 ohm resistor.



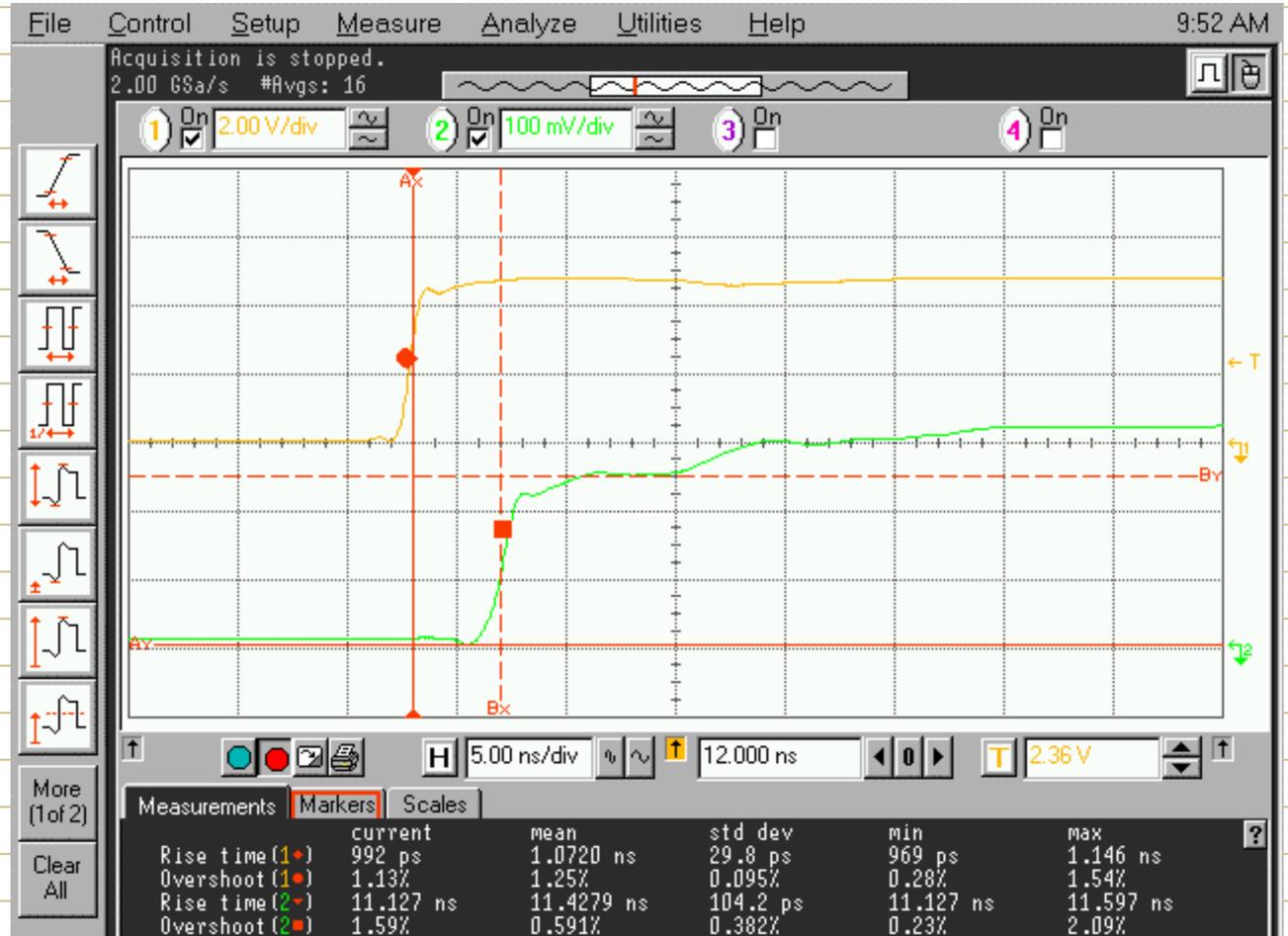
# Impedance Row B pins

File Name:

impB\_073.TIF

Trace  
terminated in  
72.7 ohm  
resistor.

(70 Ohms - Stephen  
Request)



# Impedance Row B pins

File Name:

impA\_044.TIF

Trace terminated in 44.2 ohm resistor.

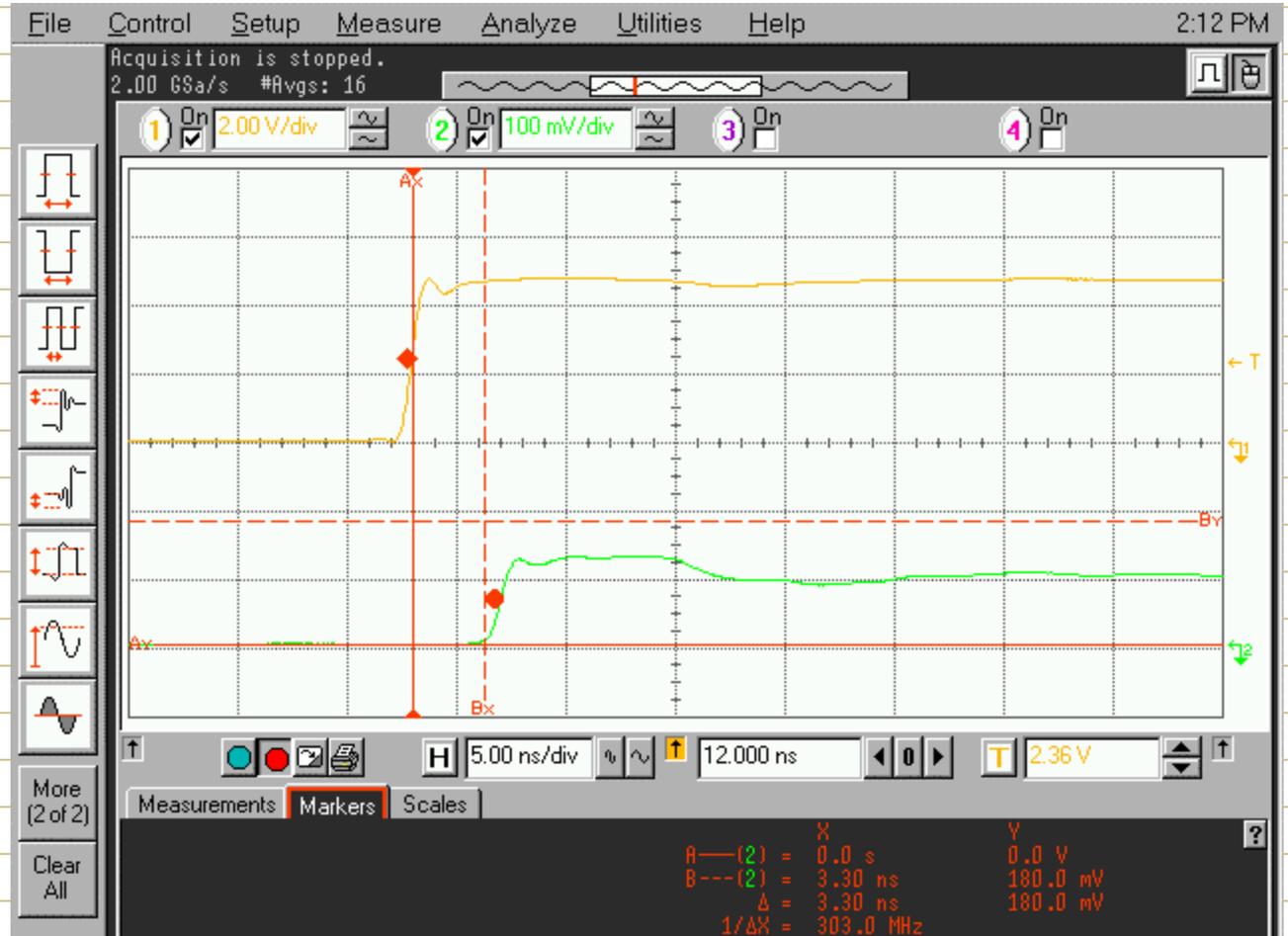


# Impedance Row B pins

File Name:

impA\_022.TIF

Trace terminated in 22 ohm resistor.

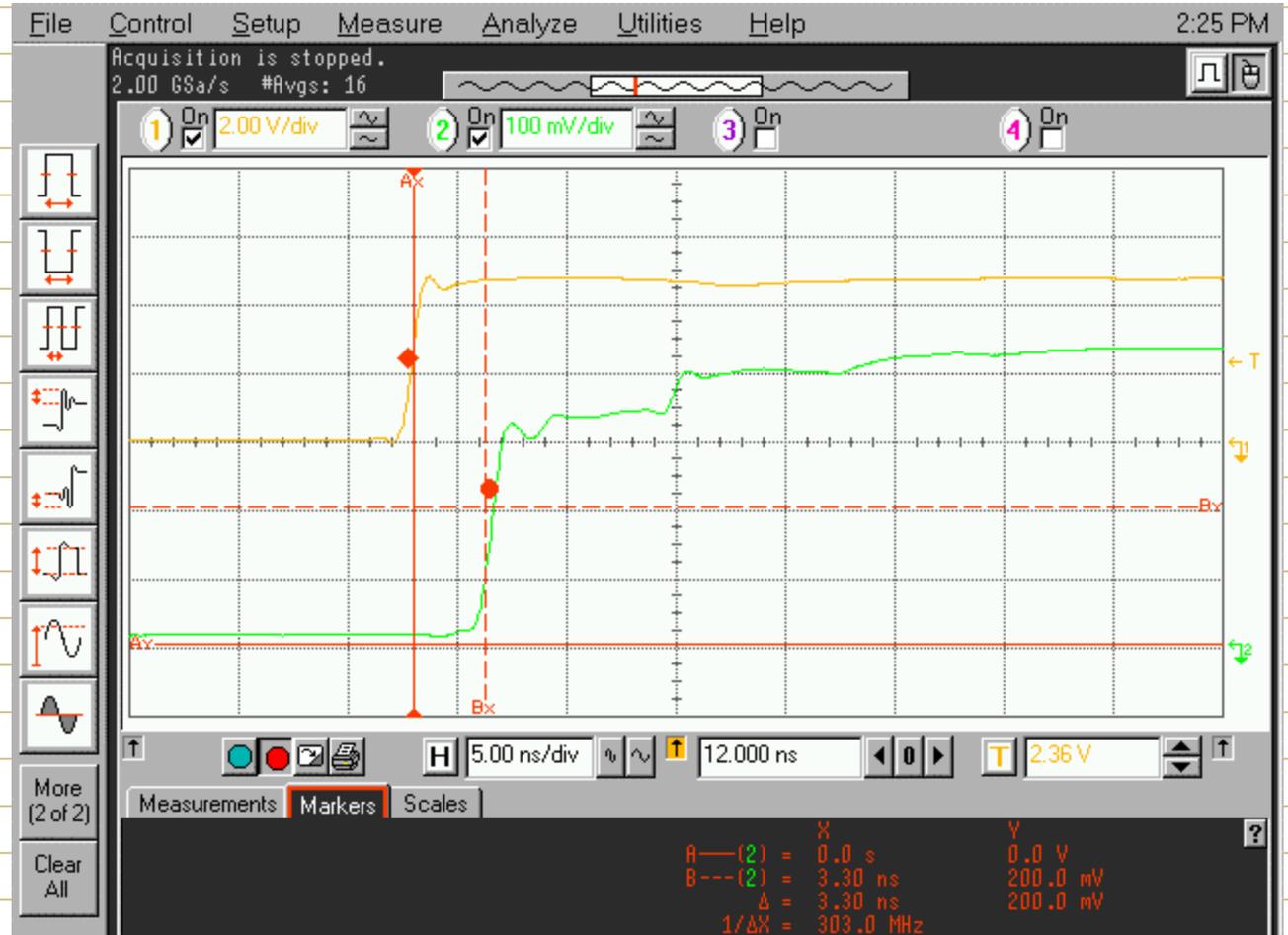


# Impedance Row C pins

File Name:

impC\_100.TIF

Trace terminated in 100 ohm resistor.



# Impedance Row C pins

File Name:

impC\_073.TIF

Trace terminated in 72.7 ohm resistor.

(70 Ohms - Stephen Request)

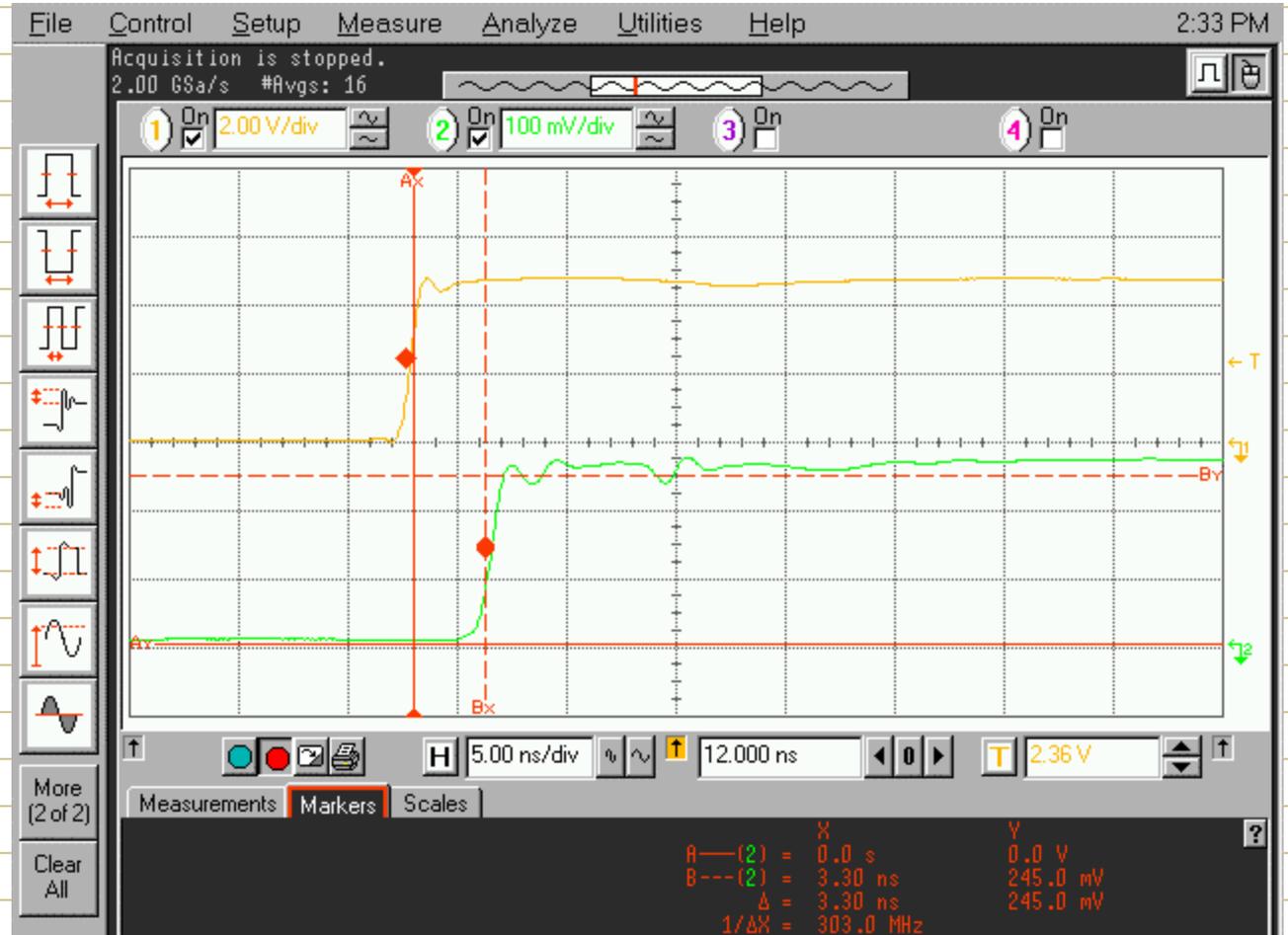


# Impedance Row C pins

File Name:

impC\_060.TIF

Trace terminated in 60 ohm resistor.

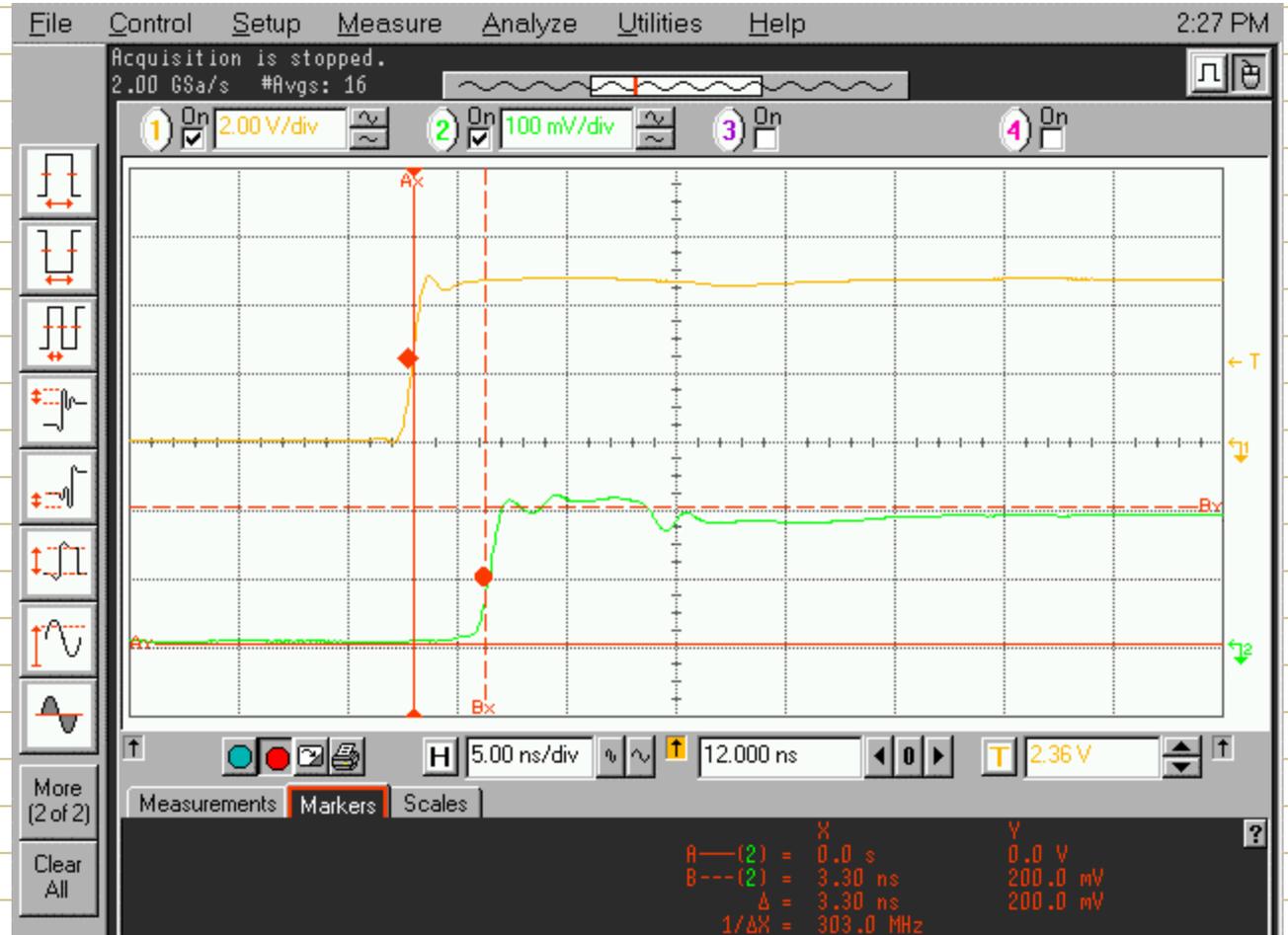


# Impedance Row C pins

File Name:

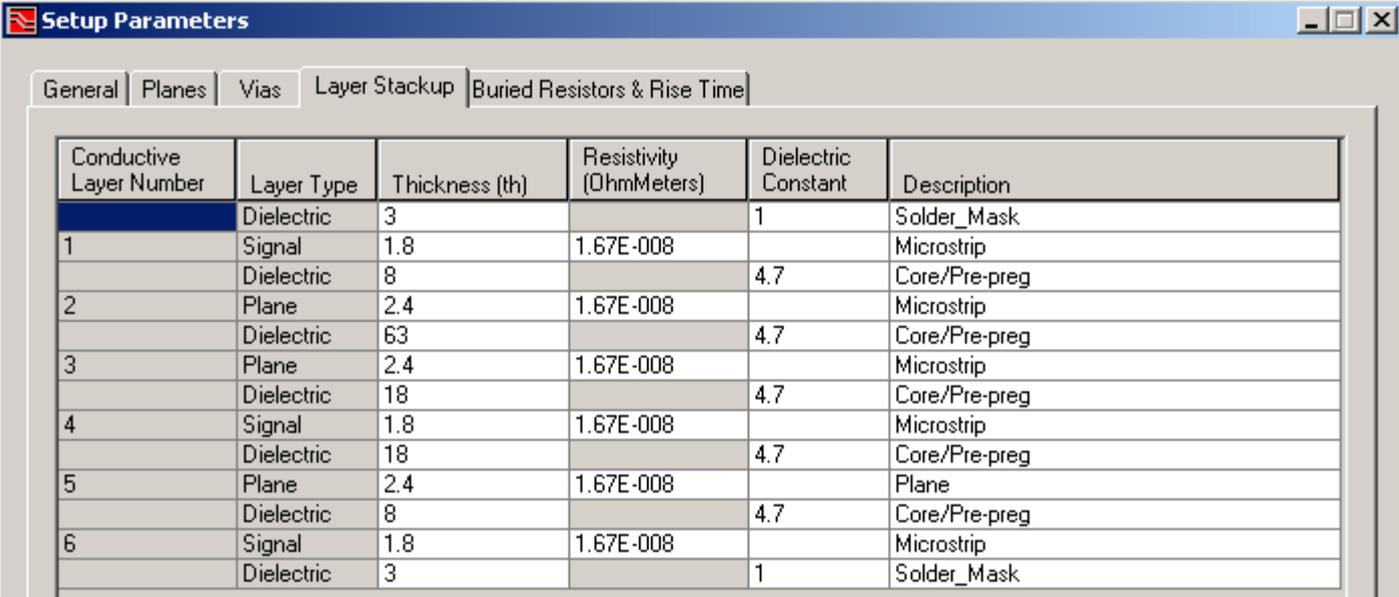
impA\_042.TIF

Trace terminated in 42 ohm resistor.



# RAD Backplane Design Checks

- ⇒ Use the layer stack/thickness numbers from the RAD fabrication drawing and create a model of the backplane in Veribest.
- ⇒ This would allow the Veribest PCB software to estimate an impedance for each trace layer.



Setup Parameters

General | Planes | Vias | Layer Stackup | Buried Resistors & Rise Time

Conductive Layer Number	Layer Type	Thickness (th)	Resistivity (OhmMeters)	Dielectric Constant	Description
	Dielectric	3		1	Solder_Mask
1	Signal	1.8	1.67E-008		Microstrip
	Dielectric	8		4.7	Core/Pre-preg
2	Plane	2.4	1.67E-008		Microstrip
	Dielectric	63		4.7	Core/Pre-preg
3	Plane	2.4	1.67E-008		Microstrip
	Dielectric	18		4.7	Core/Pre-preg
4	Signal	1.8	1.67E-008		Microstrip
	Dielectric	18		4.7	Core/Pre-preg
5	Plane	2.4	1.67E-008		Plane
	Dielectric	8		4.7	Core/Pre-preg
6	Signal	1.8	1.67E-008		Microstrip
	Dielectric	3		1	Solder_Mask

# RAD Backplane Design Checks

- ⇒ Measure PCB trace width from RAD Gerber Files.
- ⇒ All three signal layers use 6 mil (0.006") traces.

## ⇒ Veribest Estimates:

- ⇒ Row A (Layer1)  
= 71.43 Ohms
- ⇒ Row B (Layer4)  
= 65.44 Ohms
- ⇒ Row C (Layer6)  
= 71.43 Ohms

Net Classes and Clearances

Active Scheme name: (Master) Reset to (Master) options:

Net Classes Clearances

Net Class: (Default)

Via Assignments:

Via Span	(Default Via)	Net Class Via
Through	030VIA	(Default Via)

Widths & Impedance by layer:

Layers	Minimum Width	Typical Width	Typical Impedance	Expansion Width	Differential Pair Spacing
<input checked="" type="checkbox"/> Layer 1	6	6 →	71.4343	6	6
<input type="checkbox"/> Layer 2 (Plane)	8	8	115.2864	8	8
<input type="checkbox"/> Layer 3 (Plane)	8	8	47.056	8	8
<input checked="" type="checkbox"/> Layer 4	6	6 →	65.4361	6	6
<input type="checkbox"/> Layer 5 (Plane)	8	8	59.4248	8	8
<input checked="" type="checkbox"/> Layer 6	6	6 →	71.4343	6	6

# RAD Backplane Design Checks

⇒ Use microstrip design equation from “Motorola MECL System Design Handbook” to estimate trace impedance.

$$Z_o' = \frac{87}{\sqrt{e_r + 1.41}} \ln \left( \frac{5.98h}{0.8w + t} \right)$$

⇒ Assume  $e_r = 4.7$

⇒  $Z_o' = 69.7$  Ohms

⇒ Use stripline design equation from the same reference to estimate B-Row trace impedance.

$$Z_o' = \frac{60}{\sqrt{e_r}} \ln \left( \frac{4b}{0.67\pi w \left(0.8 + \frac{t}{w}\right)} \right)$$

$e_r$  = Dielectric Constant of G-10, FR-4, etc

$h$  = Trace height above ground plane

$w$  = Trace width,  $t$  = Trace thickness

$b$  = For stripline, distance between ground planes

⇒ Assume  $e_r = 4.7$

⇒  $Z_o' = 64.7$  Ohms

# Additional Impedance Measurements

- ⇒ At the previous meeting (2/01/05) there was a request to measure the trace impedance of other manufacturers VME backplanes.
- ⇒ To make more measurements, backplanes with removable termination networks would need to be found.
- ⇒ Four additional VME J1 & J2 backplanes were located and measurements completed.

# Bicc-Vero VME J2 Backplane

File Name:

BIC2\_impB\_065.TIF

Trace terminated  
in 65.3 ohm  
resistor.

Row B pins  
11 (Signal) and  
12 (Gnd).



Nasty looking signal, measurements probably not valid. (Tom Z.)

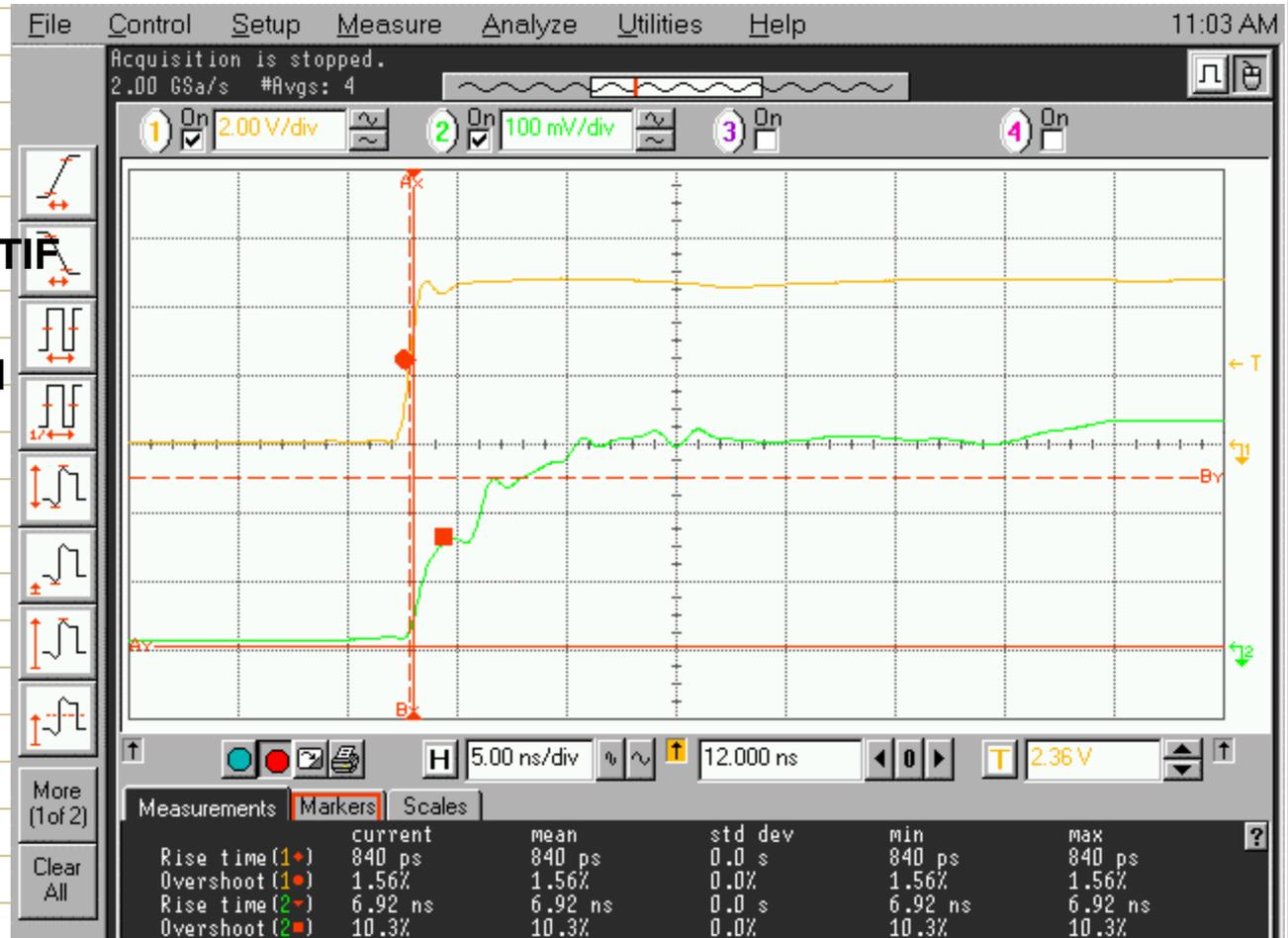
# Bicc-Vero VME J2 Backplane

File Name:

BIC2\_impB\_070.TIF

Trace terminated  
in 70.2 ohm  
resistor.

Row B pins  
11 (Signal) and  
12 (Gnd).



Measurement probably not valid. (Tom Z.) - (18pf cap added)

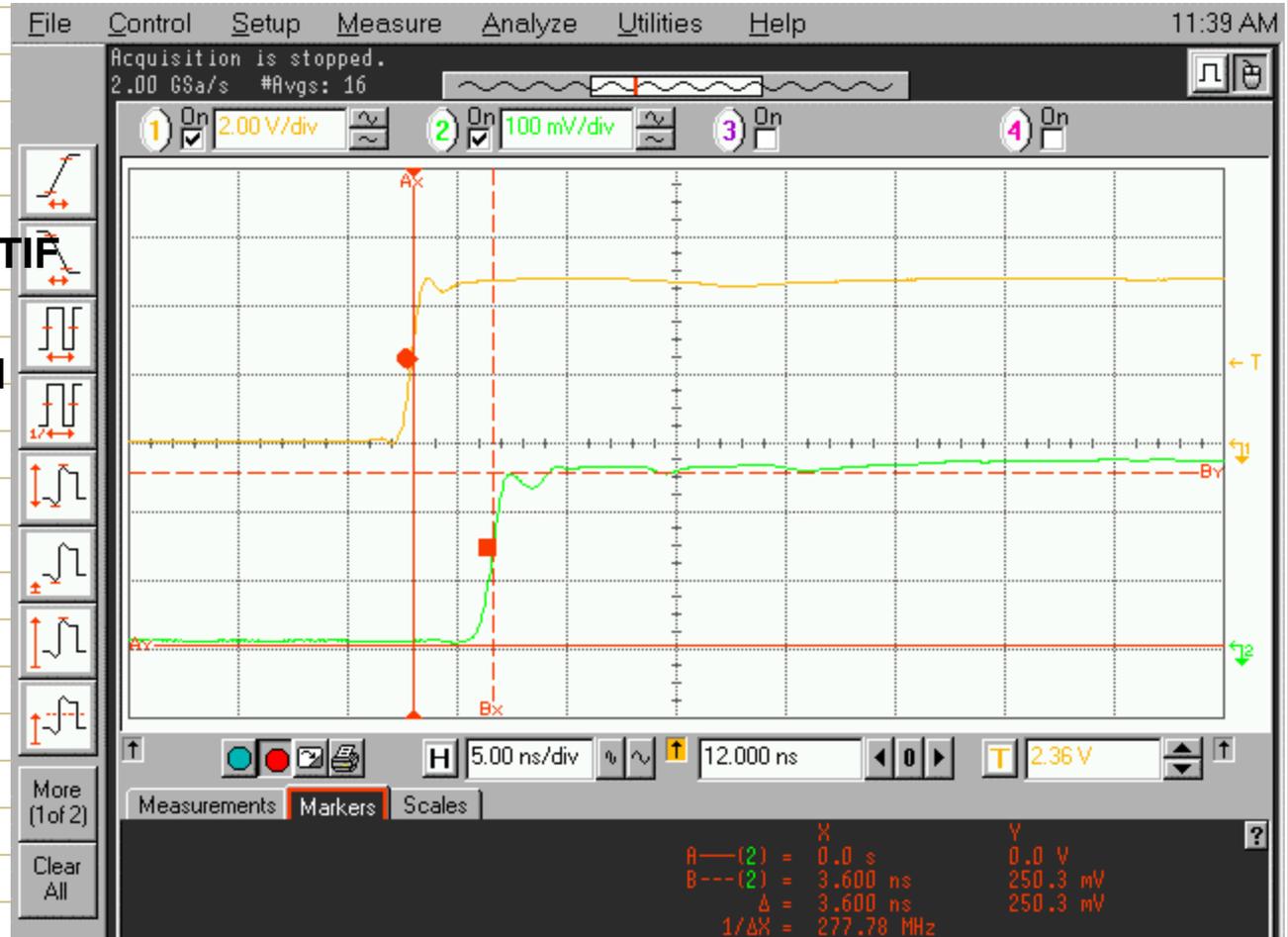
# Bicc-Vero VME J1 Backplane

File Name:

BIC1\_impA\_060.TIF

Trace terminated  
in 60.4 ohm  
resistor.

Row A pins  
8 (Signal) and  
9 (Gnd).



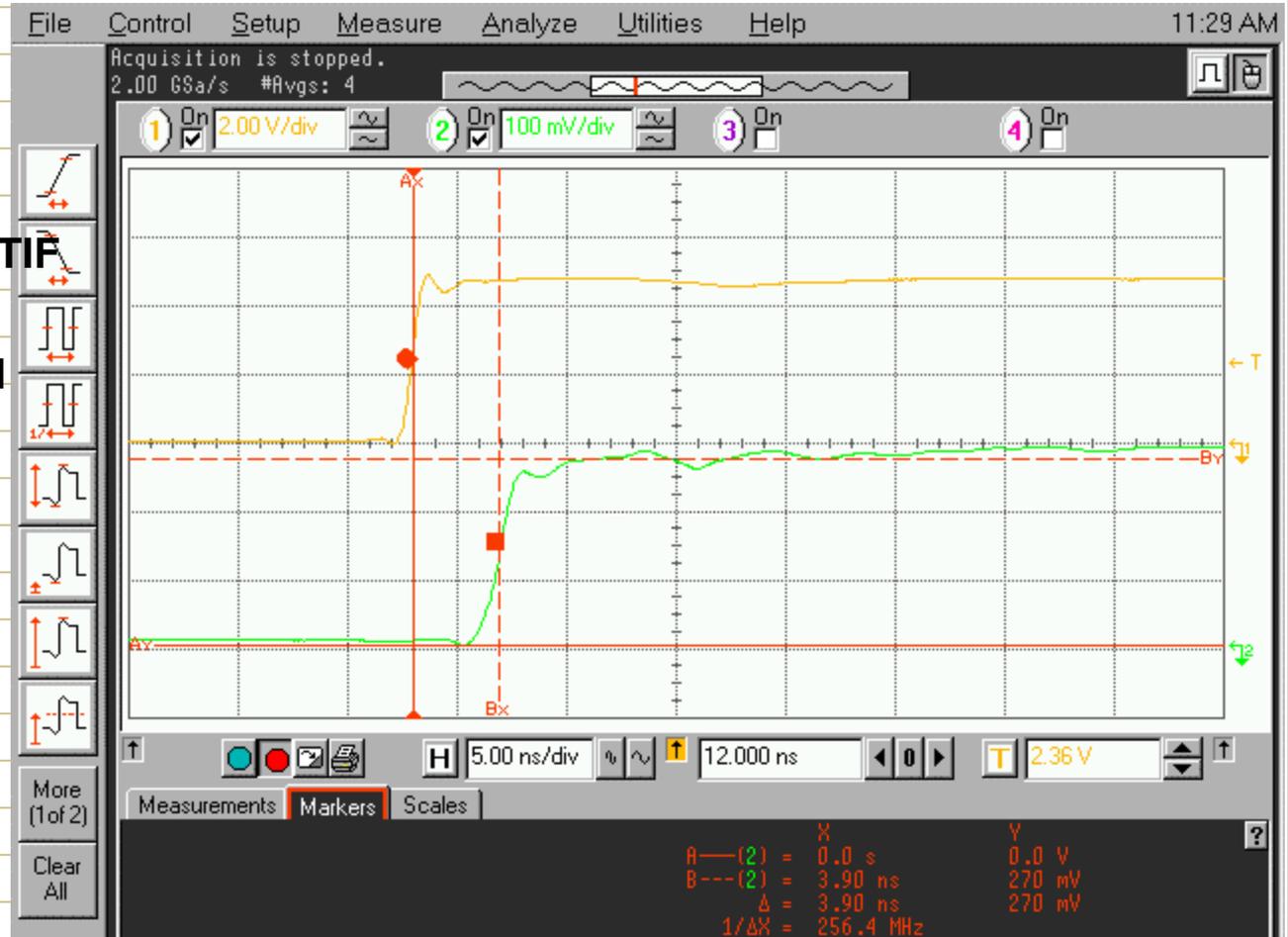
# Bicc-Vero VME J1 Backplane

File Name:

BIC1\_impB\_064.TIF

Trace terminated  
in 64.4 ohm  
resistor.

Row B pins  
19 (Signal) and  
20 (Gnd).



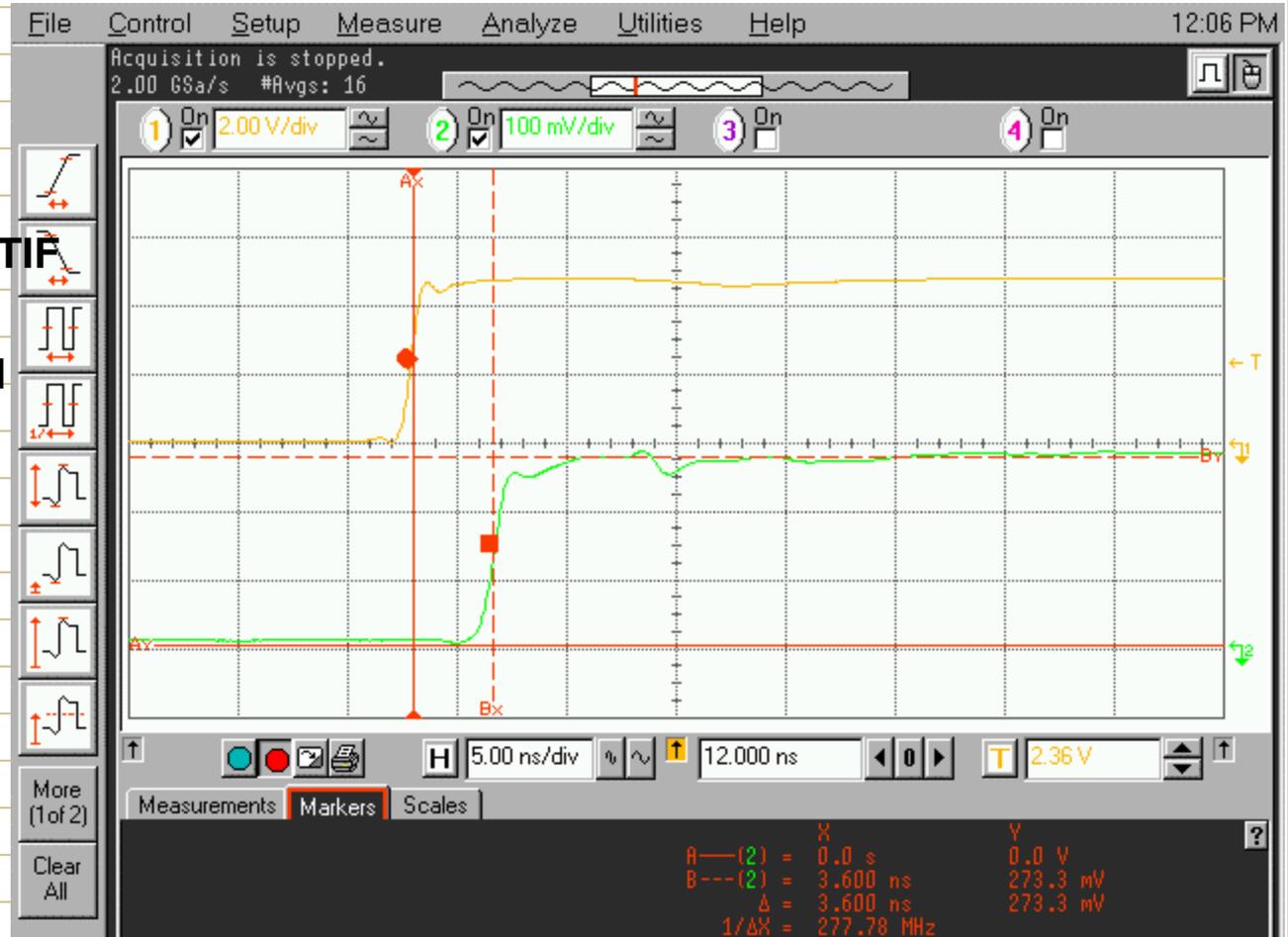
# Bicc-Vero VME J1 Backplane

File Name:

BIC1\_impC\_063.TIF

Trace terminated  
in 63.4 ohm  
resistor.

Row C pins  
8 (Signal) and  
9 (Gnd).



# Schroff VME J1 Backplane

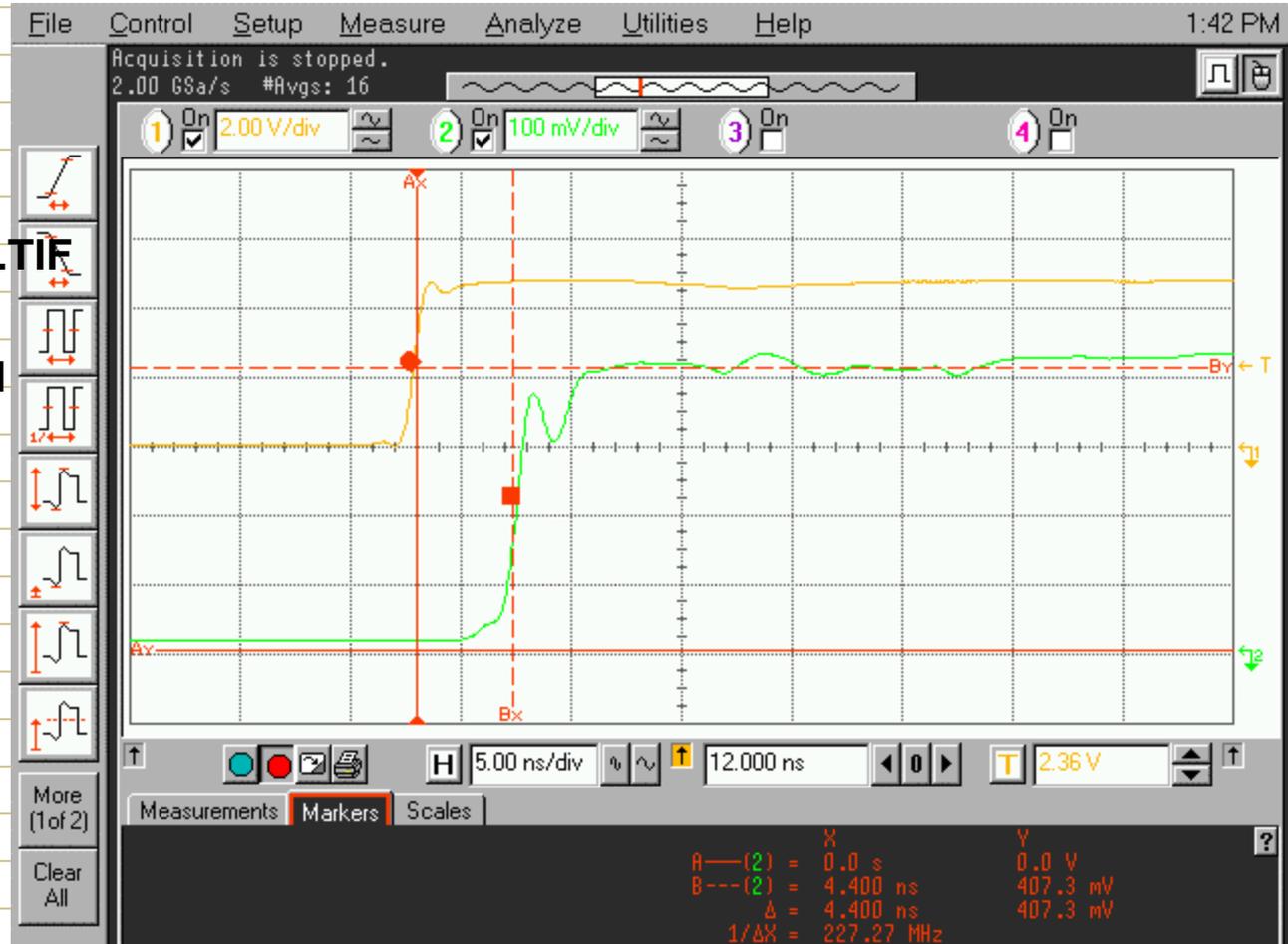
(Older Model, Wire Wrap Length Pins on Connectors)

File Name:

SCF1\_impA\_098.TIF

Trace terminated  
in 97.7 ohm  
resistor.

Row A pins  
8 (Signal) and  
9 (Gnd).



# Schroff VME J1 Backplane

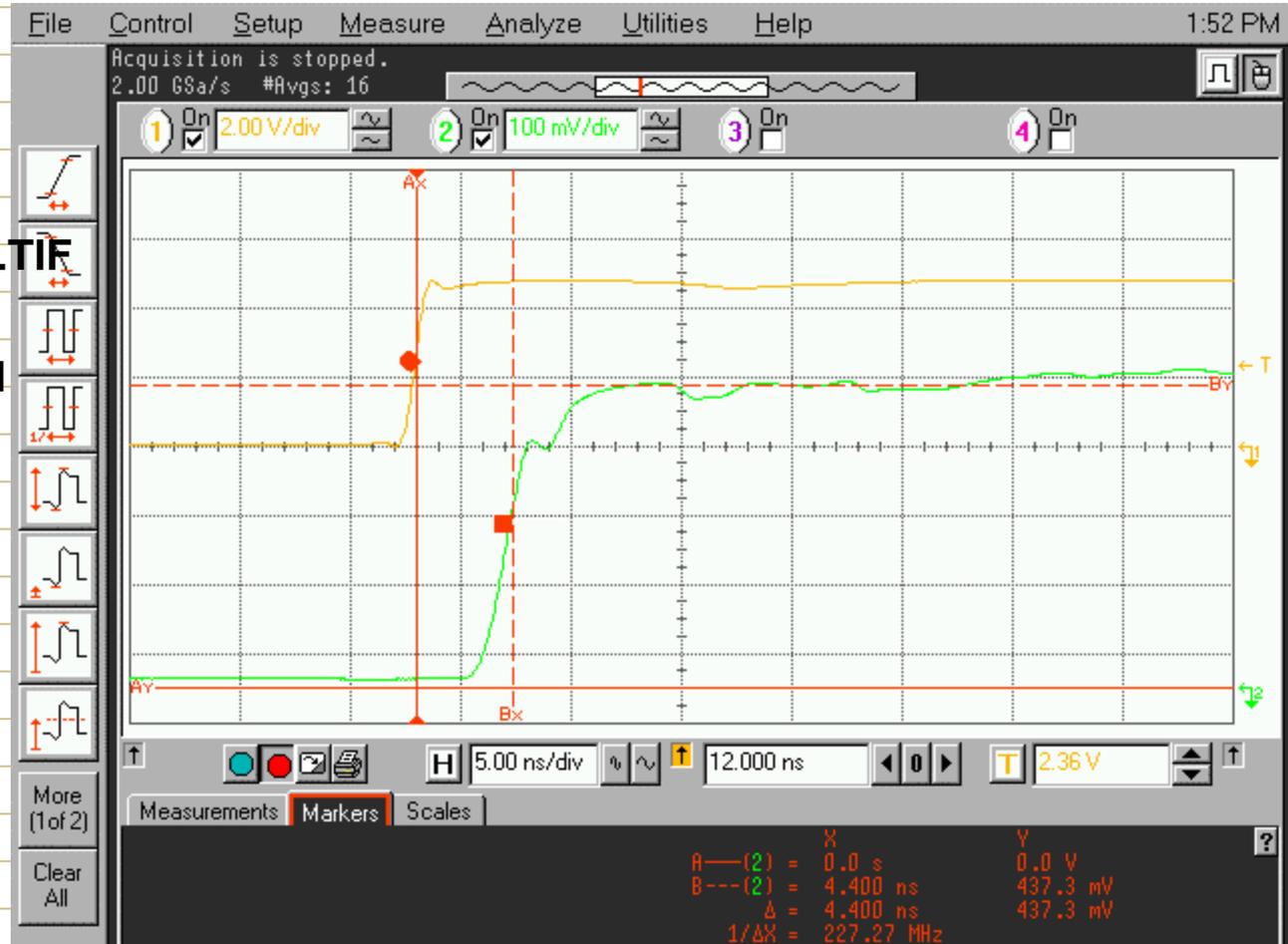
(Older Model, Wire Wrap Length Pins on Connectors)

File Name:

SCF1\_impB\_106.TIF

Trace terminated  
in 105.8 ohm  
resistor.

Row B pins  
19 (Signal) and  
20 (Gnd).



# Schroff VME J1 Backplane

(Older Model, Wire Wrap Length Pins on Connectors)

File Name:

SCF1\_impC\_100.TIF

Trace terminated  
in 100.6 ohm  
resistor.

Row C pins  
8 (Signal) and  
9 (Gnd).



# Schroff VME J1 Backplane (Model 60800-390, 20-Slots)

File Name:

SHF1\_impA\_071.TIF

Trace terminated  
in 71.3 ohm  
resistor.

Row A pins  
8 (Signal) and  
9 (Gnd).



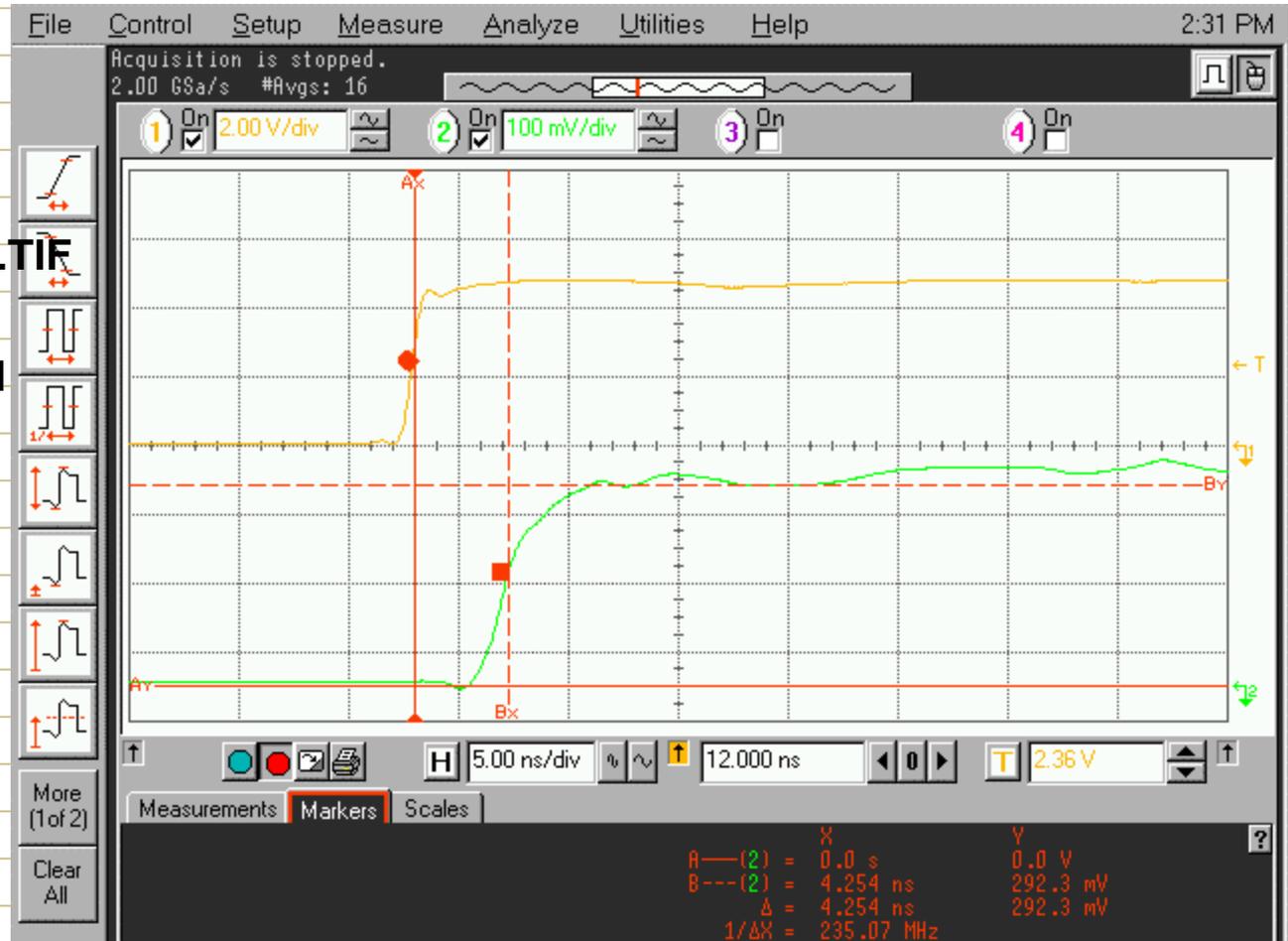
# Schroff VME J1 Backplane (Model 60800-390, 20-Slots)

File Name:

SHF1\_impB\_072.TIF

Trace terminated  
in 72.4 ohm  
resistor.

Row B pins  
19 (Signal) and  
20 (Gnd).



# Schroff VME J1 Backplane (Model 60800-390, 20-Slots)

File Name:

SHF1\_impC\_072.TIF

Trace terminated  
in 72.1 ohm  
resistor.

Row C pins  
8 (Signal) and  
9 (Gnd).



# Summary, Other Backplanes

⇒ Bicc-Vero VME J2 Backplane

⇒ Avg. Impedance = ???

⇒ Bicc-Vero VME J1 Backplane

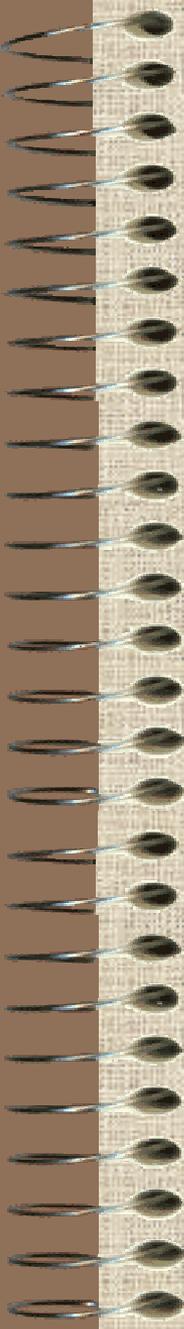
⇒ Avg. Impedance = 63.1 Ohms

⇒ Schroff VME J1 Backplane (Older Model, Wire Wrap Pins)

⇒ Avg. Impedance = 101.4 Ohms

⇒ Schroff VME J1 Backplane (Model 60800-390, 20-Slot)

⇒ Avg. Impedance = 71.9 Ohms



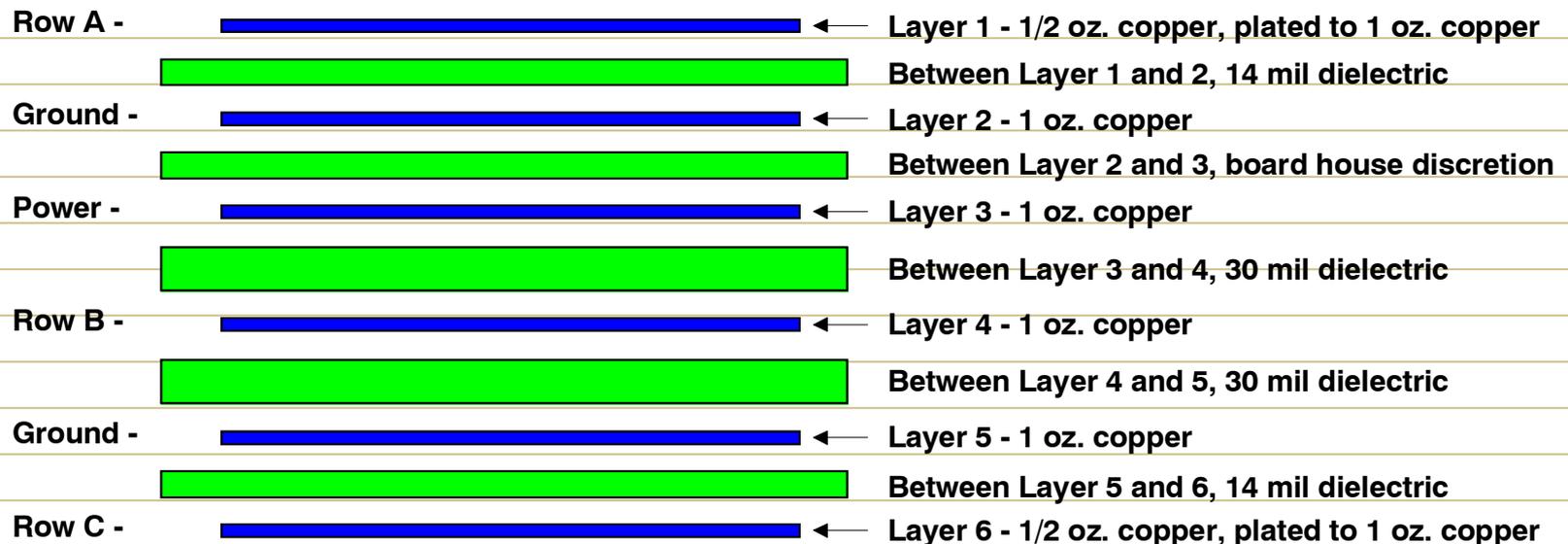
# **RAD Engineering BLM VME J2 Backplane**

**Updated Information for  
Production Backplanes**

**February 15, 2005**

# Production Backplane Layer Stack

- ⇒ **Prototype Backplane Trace Impedance was Low**
- ⇒ **RAD Engineering Proposed Different Layer Stack for Production Backplanes**
- ⇒ **Still 6 mil trace, Impedance 90 Ohms +/- 10%**
- ⇒ **Overall thickness the same at 0.125" +/- .005"**



# Production Backplane Impedance

- ⇒ **The estimated impedance for the old layer stack was approximately, ???**
- ⇒ **Estimate Prototype Backplane:**
- ⇒ **A & C Rows = 69.7  $\Omega$  , B Row = 64.7  $\Omega$**
- ⇒ **The estimated impedance for the new layer stack would be approximately, ???**
- ⇒ **Estimate Production Backplane:**
- ⇒ **A & C Rows = 90.8  $\Omega$  , B Row = 79.7  $\Omega$**

# Production Backplane Impedance

- ⇒ **Measured Impedance of Prototype Backplane:**
- ⇒ **Prototype A & C Rows = 56-60 Ohms**
- ⇒ **Prototype B Row = 44 Ohms**
- ⇒ **If the addition of the ground isolation islands, connectors, etc. lowers the estimated impedance by the same amount as on the two prototypes we should end up with a trace impedance of approximately...**
- ⇒ **Production A & C Rows = 77 Ohms**
- ⇒ **Production B Row = 60 Ohms**